

PCN Number:	20100813000XB		PCN Date:	03/28/2013	
Title:	Assembly Site move to CAR for Select Devices in the SSOP (DB) Package				
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services
Proposed 1st Ship Date:	09/28/2013	Estimated Sample Availability:	Date provided at sample request		
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Final notifications of Assembly Site move to CAR for Select Devices in the SSOP (DB) Package which are currently assembled at CRS. This also includes a change on the MSL level as follows:					
		From		To	
	Moisture Sensitivity	MSL 1, 260C		MSL 2, 260C	
Reason for Change:					
Continuity of supply.					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None.					
Changes to product identification resulting from this PCN:					
Sample Product Shipping Label (not actual product label)					
Assembly Site					
	CRS	Assembly Site Origin (22L)		ASO: CRS	
	CAR	Assembly Site Origin (22L)		ASO: CAR	
					
Product Affected:					
	PCM4202IDBREP	V62/07642-01XE			

DB Qualification Data: Approved 3/21/2013

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Device 1 : ADS1213E (MSL 2-260C)**Package Construction Details**

Assembly Site:	CAR	Mold Compound:	438360
# Pins-Designator, Family:	28-DB, SSOP	Mount Compound:	434165
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size Pass/Fail
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0
Manufacturability	(Assembly Site)	Pass
Moisture Sensitivity, L2	85C/60%RH/168 Hrs	12/0

Notes: ** Preconditioning sequence Level 2-260C

Qual Device 2 : ADS7871IDB (MSL 2-260C)**Package Construction Details**

Assembly Site:	CAR	Mold Compound:	438358
# Pins-Designator, Family:	28-DB, SSOP	Mount Compound:	434165
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size/Fail
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0
Manufacturability	(Assembly Site)	Pass
Moisture Sensitivity, L2	85C/60%RH/168 Hrs	12/0

Notes: ** Preconditioning sequence Level 2-260C

Qual Device 3 : ADS825E (MSL 2-260C)**Package Construction Details**

Assembly Site:	CAR	Mold Compound:	438360
# Pins-Designator, Family:	28-DB, SSOP	Mount Compound:	434165
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size/Fail
Solderability	Pb-Free/Solder	22/0
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0
Manufacturability	(Assembly Site)	Pass
Physical Dimensions	Mechanical drawing	5/0
Moisture Sensitivity, L2	85C/60%RH/168 Hrs	12/0

Notes: ** Preconditioning sequence Level 2-260C

Qual Device 4 : DAC8820IBDB (MSL 2-260C)					
Package Construction Details					
Assembly Site:	CAR	Mold Compound:	438518		
# Pins-Designator, Family:	28-DB, SSOP	Mount Compound:	434165		
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions	Sample Size/Fail			
		Lot 1	Lot 2	Lot 3	
Manufacturability	(Assembly Site)	Pass	Pass	Pass	
Solderability	8 Hrs/Stm Age, Pb-Free/Solder	22/0	22/0	-	
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0	77/0	77/0	
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0	
Physical Dimensions	Mechanical drawing	5/0	-	-	
Moisture Sensitivity, L2	85C/60%RH/168 Hrs	12/0	12/0	-	
Notes: ** Preconditioning sequence Level 2-260C					
Qual Device 5 : PGA2505IDB (MSL 2-260C)					
Package Construction Details					
Assembly Site:	CAR	Mold Compound:	438360		
# Pins-Designator, Family:	24-DB, SSOP	Mount Compound:	434165		
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions	Sample Size/Fail			
		Lot 1	Lot 2	Lot 3	
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0			
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0			
Manufacturability	(Assembly Site)	Pass			
Physical Dimensions	Mechanical drawing	5/0			
Moisture Sensitivity, L2	85C/60%RH/168 Hrs	12/0			
Notes: ** Preconditioning sequence Level 2-260C					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com